

SHIELDED SMD CHIP POWER INDUCTOR



14.0 x 12.9 x 6.7mm

ASPI-1367



RoHS
Compliant

FEATURES:

- 100%lead (Pb) free.
- Lowest DCR/uH, in this package size.
- Frequency range up to 5.0MHZ.
- Handles high transient current spikes without saturation
- Ultra low buzz noise, due to composite construction.

APPLICATIONS:

- PDA/Notebook/Desktop/Server applications.
- Low profile, high current power supplies.
- Battery powered devices.
- DC/DC converter for Field Programmable Gate Array(FPGA)

ELECTRICAL SPECIFICATIONS:

Goldstone P/N:	ASPI-1367
Operating Temperature:	-40°C to +125°C
Storage Temperature:	Less than +40°C, 70% RH.

Part Number ASPI-1367-	L (μ H)	Tolerance (M, N)	R_{DC} (m Ω)		I_{sat} (A)	I_{rms} (A)
			Typ	Max		
R10	0.1	N	0.25	0.5	80.0	60.0
R33	0.33	M	0.6	0.8	65.0	46.0
2R2	2.2	M	3.8	4.2	33.0	20.0
3R3	3.3	M	5.5	6.8	29.0	15.0
4R7	4.7	M	9.5	11.2	25.0	13.5
5R6	5.6	M	10.5	11.5	24.0	12.0
6R8	6.8	M	13.5	14.9	16.5	11.5
8R2	8.2	M	15.2	16.6	16.0	10.5
100	10	M	17.0	18.5	15.5	10.0

Test Conditions

1. Inductance tested at 200kHz, 0.25V, 0A; Tolerance M= \pm 20%, N= \pm 30%
2. All test data is in reference to 25°C ambient.
3. Isat will cause the inductance value to drop approximately 30%
4. Irms will cause an approximate Δ T of 40°C
5. The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Please contact Abracon for the availability of other inductance values.

OPTIONS AND PART IDENTIFICATION

ASPI-1367- -

Inductance Code
Please refer to the
Electrical Spec Table

Tolerance
M: \pm 20% *
N: \pm 30% *

Packaging
T: Tape and Reel (250pcs / reel)

*N for 0.1 μ H

*M for 0.33~10 μ H

SHIELDED SMD CHIP POWER INDUCTOR

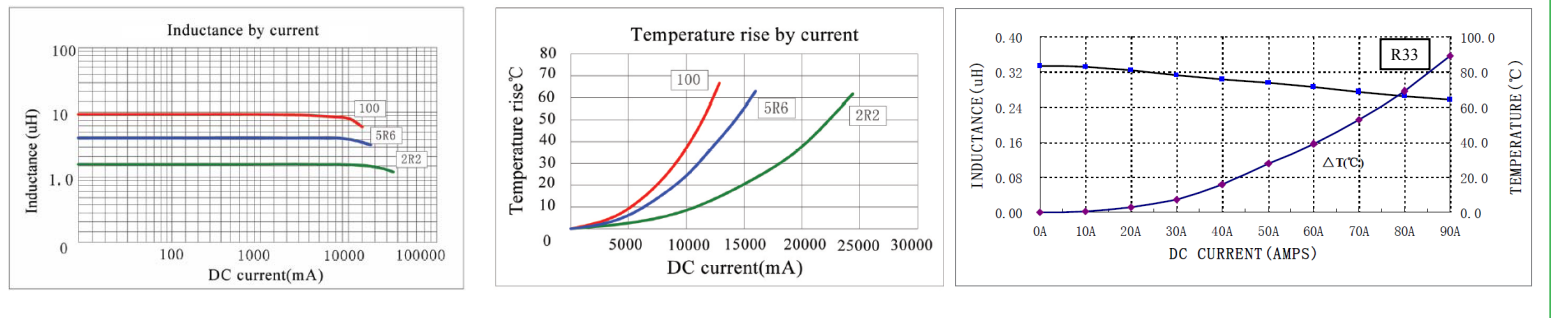


14.0 x 12.9 x 6.7mm

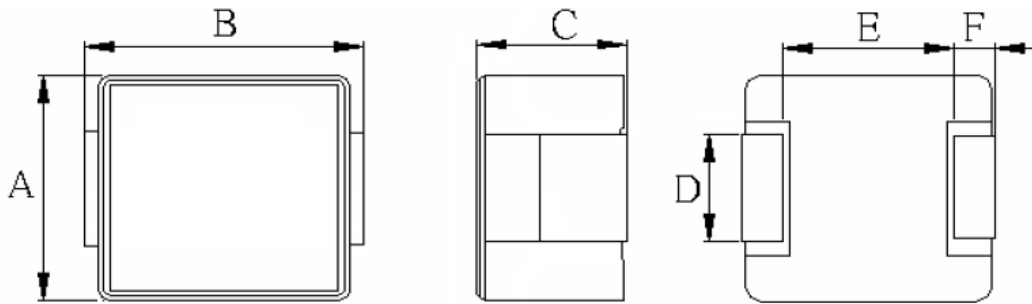
ASPI-1367

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INDUCTANCE AND TEMPERATURE CURVE

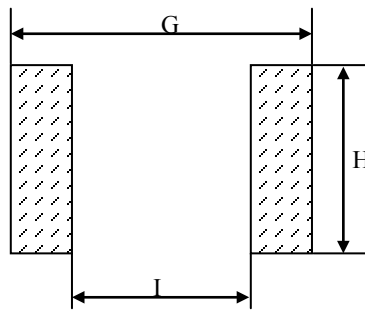


OUTLINE DIMENSIONS:



A	B	C	D	E	F
12.9 max.	14.0 max.	6.7 max.	4.0±0.5 for L≤1.5uH 3.0±0.5 for L=2.2uH 4.7±0.3 for L>2.2uH	8.4 ref.	2.0±0.5

Recommended Land Pattern



G	H	I
14.5	5.0	8.0

Dimension: mm

SHIELDED SMD CHIP POWER INDUCTOR



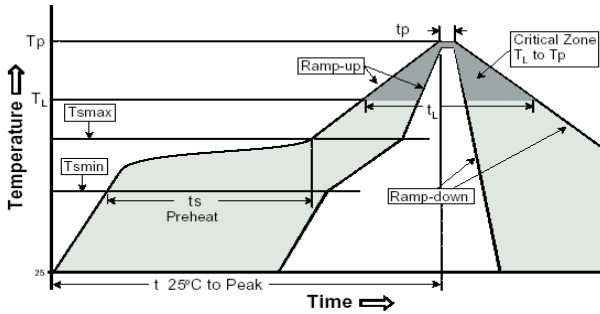
14.0 x 12.9 x 6.7mm

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REFLOW PROFILE:



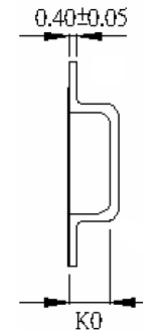
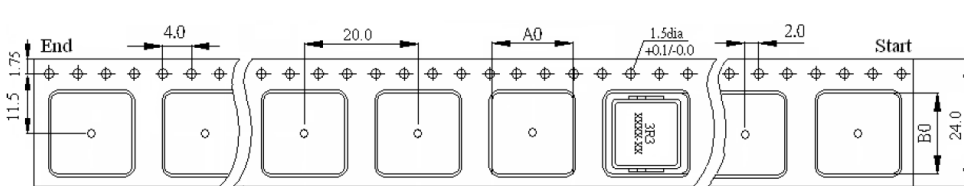
Profile Feature	Assembly
Average Ramp-Up Rate (T_{smax} to T_p)	3°C/second max.
Preheat	150°C 200°C 60-180 seconds
-Temperature Min (T_{smin}) -Temperature Max (T_{smax}) -Time (t_{smin} to t_{smax})	
Time maintained above: -Temperature (T_L) -Time (t_l)	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	245 +0°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6°C/seconds max
Time 25°C to Peak Temperature	8 minutes max.

Storage Conditions and Handling

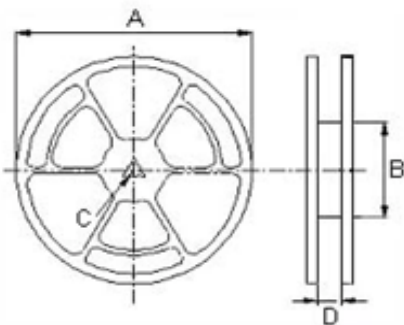
- (1) Temperature and humidity conditions : less than 40°C and 70% RH.
- (2) Products should be used within 6 months.
- (3) The packaging material should be kept where no chlorine or sulfur exists in the air.
- (4) Do not touch the electrodes (soldering terminals) with fingers as this may lead to deterioration of solder ability
- (5) The use of tweezers or vacuum pick-ups is strongly recommended for individual components.
- (6) Bulk handling should ensure that abrasion and mechanical shock are minimized.

TAPE & REEL:

T= tape and reel (250pcs/reel)



A_0	B_0	K_0
13.2	13.9	7.0



A	B	C	D
330	100	13.5	24

Dimension: mm